## Intel® 440MX Chipset For Applied Computing

The Intel® 440MX chipset represents the latest in chipset integration. By providing a cost effective, low power single-component chipset specifically designed to reduce system cost, space and power, this product is ideal for low-power, low cost applied computing platform solutions. The 440MX chipset offers designers an extremely cost effective way to enable Intel quality, reliability, and initiatives across all their low power market segments.

The 440MX chipset supports low power Intel® Celeron™ processor and Intel® Pentium® III processor designs. The 440MX is offered in the small form-factor, 492 Ball Grid Array (BGA) package with a typical power dissipation of 2.1W making it an effective solution for fanless applications.

The 440MX chipset provides advanced features like support for USB, ACPI power management and AC-97 link interface, which enable soft technologies. The chipset is a single-component that integrates the North Bridge and the South Bridge and an additional AC-97 digital link (2 channels) into one chip. It replaces the ISA interface with an 8-bit X-bus that supports KBC, SIO, and Flash memory. Figure 1 illustrates a block diagram of the 440MX platform.

## Product Highlights

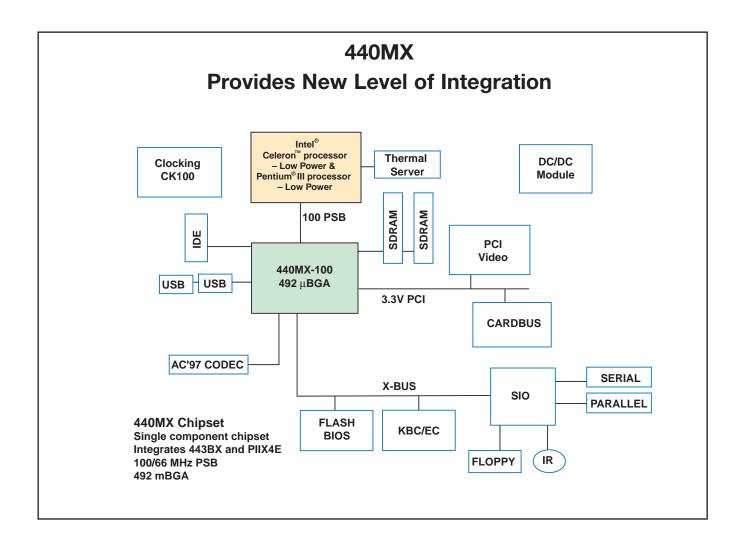
- Flexible processor support ranging from the Intel Celeron processor Low Power at 400 MHz to the Pentium III processor Low Power at 700 MHz and beyond with support for 66 or 100 MHz Processor Side Bus (PSB) speeds
- Offers power management options such as ACPI and Suspend To RAM (STR)
- Supports highly integrated single chipset combining north and south bridges

- Lower power small total footprint
- Based on the Intel® 440BX AGPset Core Architecture
- Integrated DRAM controller
- Supports up to 100 MHz SDRAM
- 256 MB maximum memory
- AC'97 Host Controller
- Power Management
- PCI Rev 2.2 Compliant
- 4 PCI Bus Masters
- Integrated IDE Controller for Ultra DMA/33
- Integrated USB Controller
- Low Cost PCI Graphics
- SMBus Interface
- 492 BGA
- 3.3-V core and mixed 3.3V with 5.0-V tolerant and GTL I/O Buffers
- 2.1W (at 100 MHz) and 1.6-W (at 66 MHz)
   TDP (typical) power dissipation with low-power features enabled



## LINECARD

PRODUC	T PRODUCT CODE	PACKAGE	FEATURES
440MX	FW82443MX100	492 BGA	<ul> <li>Combines the 440BX AGPset core architecture and PIIX4 south bridge into a single chip</li> <li>Advanced power management features</li> <li>AC-97 link interface based on Intel AC'97 Specification v 2.1</li> <li>BOM cost savings</li> </ul>



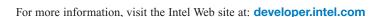
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